

# STRUCTURE OF HEAT SLUG-EQUIPPED PACKAGES AND THE PACKAGING METHOD OF THE SAME

## Field of the Invention

The present invention relates to a semiconductor package, more particularly, to a semiconductor package which can improve the efficiency of spreading heat.

## Background of the Invention

In light of the trend of smaller and smaller-sized electronics devices, conventional discrete circuits are narrowly fabricated into a silicon-based or GaAs-based wafer using integrated circuits technology. The advent of the ULSI era in chip density has forced a radical upgrading of semiconductor processing technology. An integrated circuits chip itself is very tiny in dimension and fragile in itself. There is a desire, for practical applications, to “wrap it up” to prevent it from external force or environmental factors, which may cause the chip electrically or physically damaged. Meanwhile, it is needed to connect the chip to other external circuits to make the circuits combined with on-chip and off-chip circuits, forming a device to perform a specific function. The technology “Electronic packaging”, puts the two forgoing needs into realization, which not only makes the chip properly located and well connected to the external circuits, but also forms connections between the chip and external circuits.

Objectives of the IC chips packaging designs are not only to provide a substantial lead system, physical protection, environmental protection, but also to provide a heatsink for the chip.

For the present, electronic products have a trend to be becoming slighter and smaller. To satisfy the above requirements, integrated circuits technologies have been progressing in producing high-density, high-speed, high-capacity and light chips. The increasing power dissipation from on-chip circuits arouses an issue the IC is over-heated, which would make some electronic components walk off the range which they may always feature at normal temperature. Some components have changes in their properties, and some, even, get damaged perpetually. There is an expectation to deal with such a heat-spreading problem in packaging technology as the increase on speed of the current IC packages.

FIG. 1 shows a conventional package which includes a substrate 2, a die 4 formed on the substrate via die attach epoxy 6. The die is electrically connected to the substrate 2 through gold wire bonds 8. Solder balls 10 for signal transfer is formed on the bottom surface of the substrate 2. Molding compound 12 is used to cap the die 4 and gold wire bonds 8 for protection purpose. Heat from the die 4 is spread by using thermal vias 14 in the substrate 2 and thermal balls 16 connected to the thermal vias 14. However, the heat generated by components in the die is increased due to the increasing packaging density. This also causes the conventional package to fail to satisfy the future demands.

As the semiconductor production continuously grows, many structures of packages are suggested. Among them, a plastic molded package can be found, as described in U. S. Patent No. 5586010. Another structure of package is disclosed in U. S. Patent No. 5629835 to Mahulikar et al., entitled "METAL BALL GRID ARRAY PACKAGE WITH IMPROVED THERMAL CONDUCTIVITY".

For the present, conventional packages such as SOP, PQFP-type packages are not able to further increase the number of the lead frames around them. For the sake of more lead frames, the current packaging technology has turned to BGA-type packages. The BGA package is featurized by its spherical I/O-functioned leads, which are shorter, and hence with higher speed, and not apt to become deformed. Therefore, the BGA packaging is well-suited for the future packaging topology. The spherical leads of the BGA are arranged as an array,

but not circumferentially about the package as conventional lead frames are. Consequently, the BGA can readily increase the spherical balls on it. Coupled with the larger pitches, the BGA are a rather competitive candidate as considered a current and future packaging type. Many proposals for an improved heat-spreader equipped BGA package are put forth. For example, kinds of heat slugs, heat sinks in any shape are attached to packages or packaging structures to improve the efficiency of spreading heat from packages.

Fig.2 shows the package in the prior art 2. Two wings of the heat spreader 32' is fixed on the substrate 20' by a soft material, and thus the heat spreader 32' is well supported. Then the substrate 20' and the heat spreader 32' is sealed with molding compound 30' but the top side of the heat spreader 32' exposed. Actually, there are many holes (not shown) through the heat spreader 32', and molding compound 30' is driven into the heat spreader 32' therethrough. Unfortunately, there may be defects on the molding compound 30' (e.g. some air may left in the molding compound), which would make the thermally conductive paths between the molding compound 30' and the heat spreader 32' discontinuous. The heat resistance between them is thus risen, and which makes the efficiency of heat spreading poor. Additionally, two wings of the heat spreader 32' are sealed within the molding compound 30' but only the top surface at the center of the heat spreader 32' exposed to the ambient, which further worsens the efficiency.

As the increase on speed for the current and future integrated circuits, the current heat-spreading mechanisms are expected to be further improved. To settle the problem of heat spread in a package, the present invention suggests two structures with high-performance capability of spreading heat from a package, which are different from those in prior arts on their fabrication processes and structures.

## Summary of the Invention

It is an objective of the present invention to provide heat slug equipped packaging structures, which are able to sink more heat from a package as compared to those used in prior arts.

There are two structures proposed to enhance the efficiency of spreading heat in accordance with this invention. Different from the process used in prior arts attaching a heat slug atop the substrate before molding process, the present process is to mold on the die to protect it and to proceed with heat slug attachment in this invention. By enlarging the area of the heat slug contacted with ambient air, the efficiency of spreading heat is apparently risen. However, in the prior art, large parts of the area of the heat sink embedded in the molding compound layer, and hence less area contacted with the ambient. Obviously, the evidence tells the proposed structures show better performances in reducing thermal resistance between the junctions of transistors in the chip and the ambient, and hence achieve improved heat sink equipped packaging structure.

### Brief Description of the Drawings

The foregoing aspects and many of the attendant advantages of this invention will become more readily appreciated as the same becomes better understood by reference to the following detailed description, when taken in conjunction with the accompanying drawings, wherein:

FIG. 1 is a cross-sectional diagram of a heat sink equipped package in accordance with the prior art 1.

FIG. 2 is a cross-sectional diagram of a heat sink equipped package in accordance with the prior art 2.

FIG. 3 is a cross-sectional diagram of the heat sink equipped package in the first embodiment in accordance with the present invention.

FIG. 4 is a cross-sectional diagram of the heat sink equipped package in the second embodiment in accordance with the present invention.

FIG. 5a is a diagram representative of die bonding process representative of in the manufacturing process flow of the heat sink equipped package in the preferred embodiment in accordance with the present invention.

FIG. 5b is a diagram representative of wire bonding process in the manufacturing process flow diagram of the heat sink equipped package in the preferred embodiment in accordance with the present invention.

FIG. 5c is a diagram representative of molding process in the manufacturing process flow diagram of the heat sink equipped package in the preferred embodiment in accordance with the present invention.

FIG. 5d is a diagram representative of assembly process of the heat-spreader in the manufacturing process flow of the heat sink equipped package in the preferred embodiment in accordance with the present invention.

FIG. 5e is a diagram representative of ball placement process in the manufacturing process flow of the heat sink equipped package in the preferred embodiment in accordance with the present invention.

FIG. 5f is a diagram representative of singulation process in the manufacturing process flow diagram of the heat sink equipped package in the preferred embodiment in accordance with the present invention.

### **Detailed Description of the Preferred Embodiment**

The present invention discloses two packaging structures each equipped with a heat slug, and their manufacturing processes.

Turning to Fig. 3, which depicts the cross section view of the package in the first embodiment. As shown therein, the package 10a includes a substrate 20. A semiconductor



Ball grid array (BGA), preferably a solder bump array 28, is formed on the lower-sided surface of the substrate 20 by conventional positioning technique and using a solder re-flow operation. The solder bumps 28 are used for electrically coupling to the chip 22. It is appreciated that metal alloy can be used to act for the solder bumps 28. Typically, at an end of each conductive trace on the substrate 20 is connected to one of the solder bumps 28. Solder bumps 28 are terminals of the foregoing electrical conductive paths which permit electrical signals to transfer to the chip 22. In general, the solder bumps 28 are arranged in a matrix array configuration.

In the preferred embodiment of the invention shown in Fig.4, there exists a downward bump 31 at the center of the heat slug which is geometrically different from the heat slug shown in Fig. 3. The compound 30 has a recessed portion to receive the downward bump 31. The bump 31 makes the heat slug near the top side of the die 22, and thus conducts heat from the die 22 more efficiently. It is noted that the bump 31 should not attach tightly to the die 22, but should have some spacing from the die 22 to prevent the die 22 from rubbing against the bump 31 caused by the different thermal expansion coefficient. A thermally conductive glue can be added between them and isolate them. .

Referring to Fig. 5a-5f, which depicts the manufacturing process of the structure in the second embodiment of the invention. The process starts with die bonding as shown in Fig. 5a, and is then succeeded by wire bonding as shown in Fig. 5b, molding as shown in Fig. 5c, and then by assembly of heat-spreading device as shown in Fig. 5d . The assembly process begins with priming a thermally conductive glue 48 on the concave of the molding compound 30. Next with fixing the heat-spreading device 32 onto the molding compound 30 and the glue 48 by a vacuum pick head 52. The glue 48 is acted as an intermediate layer for conducting heat from the die to the heat-spreading device, which then conducts heat away from the package to the ambient.

The prototype of the structure is appeared with the finishing of the assembly for heat-spreading device. Then ball placement is undertaken to connect external circuits by

implanting solder balls onto the conductive plate below the substrate as shown in Fig. 5e. Finally with singulation to obtain individual packages from batches of packages in the manufacturing flow, which is shown in Fig. 5f. The method of the structure in the first embodiment is similar to the one in the second embodiment.

Finally, the comparison on their thermal performances among the three packages is showed in Table 1. 5.0W power is applied to the tree packages respectively with the ambient temperature of 22°C, and with their heat spreaders 32' made of aluminum and copper. The package in the prior art 2 shows a thermal resistance of 16.72 °C/W, and 18.83 °C/W for aluminum and copper-made heat spreader respectively. The package in the first embodiment is 16.53 °C/W and 16.28 °C/W. The package in the second embodiment is 15.71 °C/W and 15.34 °C/W. By data measured and shown above, the two packaging structures put forth in the present invention are obviously superior to the packaging structure used in the prior art 2.

Structure	Material for the heat-spreading device / Parameters concerned	P	$\theta_{ja}$	$T_j$ (°C)
Prior Art 2	Aluminum	5.0	16.72	105.6
	Copper	5.0	18.83	
The First Embodiment	Aluminum	5.0	16.53	104.65
	Copper	5.0	16.28	103.38
The Second Embodiment	Aluminum	5.0	15.71	100.56
	Copper	5.0	15.34	98.69

Table 1

As is understood by a person skilled in the art, the foregoing preferred embodiments of the present invention are illustrated of the present invention rather than limiting of the



present invention. It is intended to cover various modifications and similar arrangements included within the spirit and scope of the appended claims, the scope of which should be accorded the broadest interpretation so as to encompass all such modifications and similar structures.